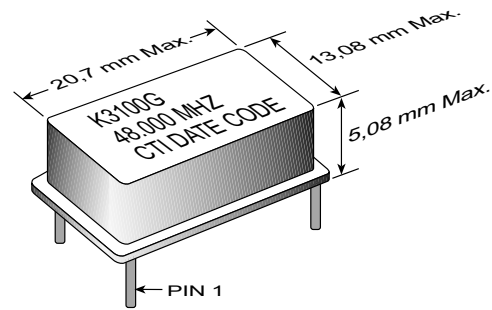


- TTL/CMOS Compatible
Tight Symmetry (45/55%) Available
- Tri-State Option Available
- ± 100 ppm Stability Standard - K3100GC
Tighter Stabilities Available
 ± 25 ppm Stability:- K3100GA
 ± 50 ppm Stability:- K3100GB
- Case Ground for EMI Protection



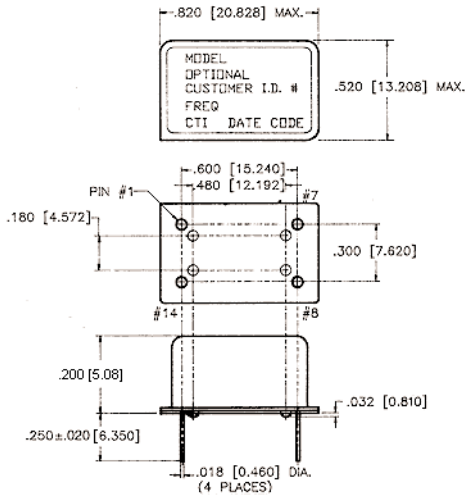
ELECTRICAL SPECIFICATIONS

MODEL	K3100GA	K3100GB	K3100GC
Frequency Range (MHz)	1.0 to 125		
Frequency Stability (ppm)			
Overall	Inclusive of calibration, temperature, voltage, load, shock,vibration, aging		
0°C to 70°C	± 25	± 50	± 100
-40°C to 85°C	N/A	± 50	± 100
Temperature Range (°C)			
Operating	-40°C to +85°C		
Storage	-55°C to +125°C		
Supply Voltage (V)	+3.3 $\pm 5\%$		
Supply Current (mA)	<30		
Output CMOS			
"0" Level (V_{OL})	0.9 V_{CC}		
"1" Level (V_{OH})	0.1 V_{CC}		
Load	Up to 80MHz 50pF; >80MHz 30pF		
T_R & T_F (ns)	<10		
Symmetry (%)	40/60		
Jitter (Typical)	10ps RMS @ 100MHz		
Start up Time (ms)	<10		

PART NUMBERING GUIDE

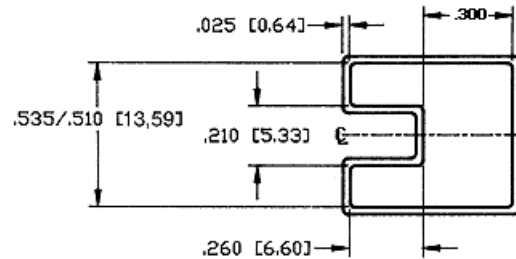
K3100GXXXX - Specify Frequency

Blank	= Fixed Frequency
E	= Tri-State
Blank	= 0°C to 70°C Operating Temperature
M	= -40°C to 85°C Operating Temperature
Blank	= 40/60% Symmetry
S	= 45/55 Symmetry
A	= ± 25 ppm Frequency Stability (Available 0/70°C only)
B	= ± 50 ppm Frequency Stability
C	= ± 100 ppm Frequency Stability



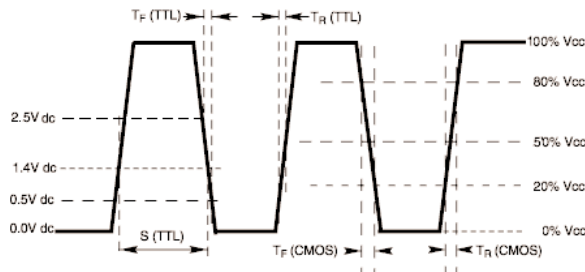
PIN	FUNCTION
1	N/C / Tri-State
7	Ground
8	Output
14	+V _{CC}

SHIPPING TUBE CROSS SECTION

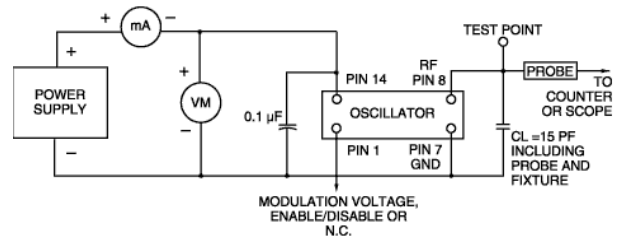


ALL DIMENSIONS ARE INSIDE

OUTPUT WAVEFORM



TEST CIRCUIT DIAGRAM



MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS

TEST METHODS	REFERENCE PROCEDURES	DESCRIPTION
Temperature Cycle	MIL-STD-833, Mtd 1010, Cond. B	-55°C to +125°C; Air-to-Air; 100 cycles; 10 min. dwell
Mechanical Shock	MIL-STD-883, Mtd 2002, Cond. B	1500 g's
Vibration	MIL-STD 883, Mtd 2007, Cond. B	20-2000 Hz; 0.06 inch; 15g's; 3 planes
Humidity Steady State	MIL-STD-202, Mtd 103	40°C; 90%-95% R.H.; 56 days
Thermal Shock	MIL-STD-883, Mtd 1011.7 Cond. B	100°C to 0°C; Water-to-Water; 15 cycles
Electrostatic Discharge	MIL-STD-883, Mtd 3015 Class II	2 KV to 4 KV Threshold
Solderability	MIL-STD-883, Mtd 2022.2	Solder dip; Meniscograph Criteria
Hermeticity	MIL-STD-883, Mtd 1014.8, Cond. A1	Mass spectro. 2 x 10 ⁻⁸ atmos. CC/sec He
Resistance to Soldering	MIL-STD-202, Mtd 210D, Cond. J	235°C; 30 seconds
Lead Integrity	MIL-STD-883, Mtd 2004.5, Cond. A, B1	Lead tension & bend stress
Marking Permanence	MIL-STD-883, Mtd 2015.8	Resistance to solvents
Life Test	MIL-STD-883, Mtd 1005.6	125°C, powered, 1000 hours minimum